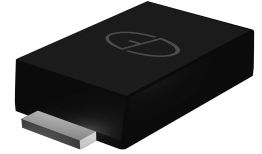


## Features

- Low  $V_F$  schottky barrier rectifiers
- Low profile - typical height 1.0 mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- AEC-Q101 qualified
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition



Package: eSGA  
(SOD-123FL)

## Applications

For use in fast switching in RF module, lighting, cell phone, portable devices, power supply and other consumer applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter   | Symbol              | FS2B5H      | FS2CH | Unit             |
|---|---------------------|-------------|-------|------------------|
| Maximum Repetitive Peak Reverse Voltage   | $V_{RRM}$           | 150         | 200   | V                |
| Maximum RMS Voltage   | $V_{RMS}$           | 105         | 140   | V                |
| Maximum DC Blocking Voltage   | $V_{DC}$            | 150         | 200   | V                |
| Maximum Average Forward Rectified Current   | $I_{F(AV)}$         | 2.0         |       | A                |
| Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load | $I_{FSM}$           | 50          |       | A                |
| Operating Junction and Storage Temperature Range                                  | $T_J,$<br>$T_{STG}$ | -55 to +150 |       | $^\circ\text{C}$ |

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter   | Test Conditions         | Symbol          | Value | Unit               |
|---|-------------------------|-----------------|-------|--------------------|
| Maximum Instantaneous Forward Voltage                   | $I_F=2A$                | $V_F$           | 0.85  | V                  |
| Maximum DC Reverse Current at Rated DC Blocking Voltage | $T_A=25^\circ\text{C}$  | $I_R$           | 200   | $\mu\text{A}$      |
|   | $T_A=125^\circ\text{C}$ |                 | 30    | mA                 |
| Typical Thermal Resistance <sup>1)</sup>                | Junction to Ambient     | $R_{\theta JA}$ | 85    | $^\circ\text{C/W}$ |
|   | Junction to Case        | $R_{\theta JC}$ | 45    |                    |
|   | Junction to Lead        | $R_{\theta JL}$ | 20    |                    |

Note:1) The thermal resistance from junction to ambient, case or mount, mounted on P.C.B with 5×5mm copper pads, 2 OZ, FR4 PCB

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

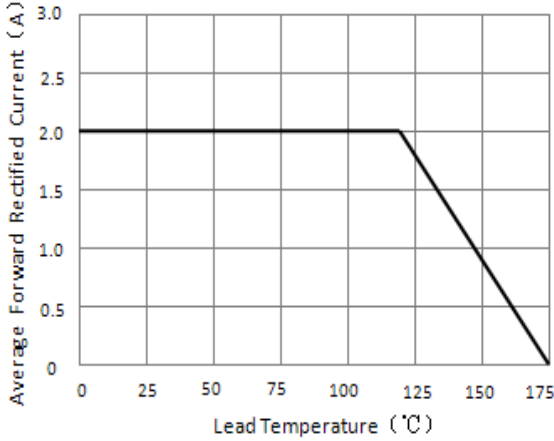


Figure 1. Forward Current Derating Curve

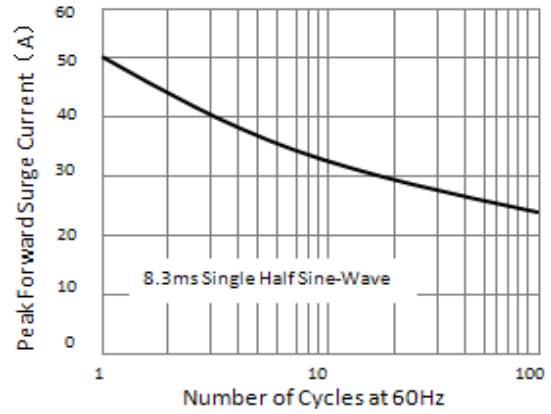


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

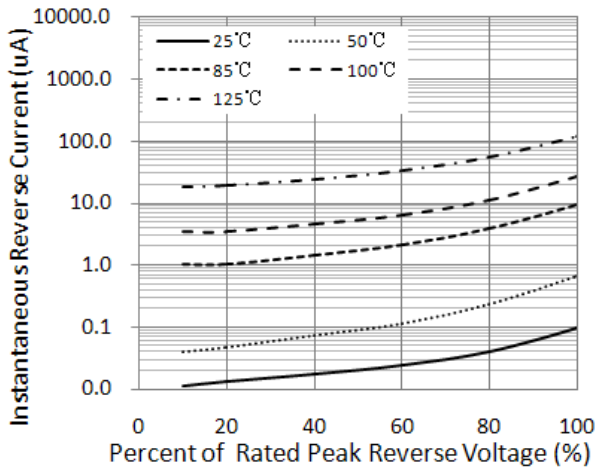


Figure 3. Typical Instantaneous Reverse Characteristics

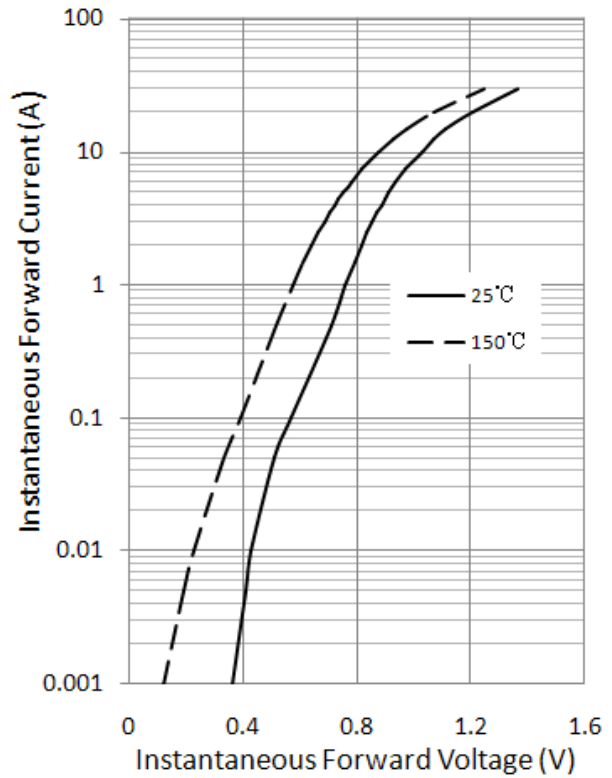


Figure 4. Typical Instantaneous Forward Characteristics

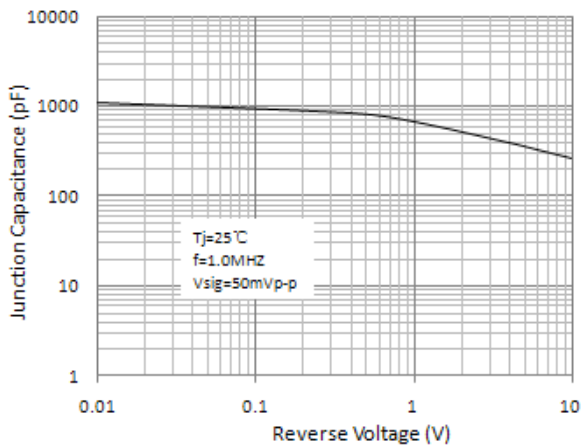
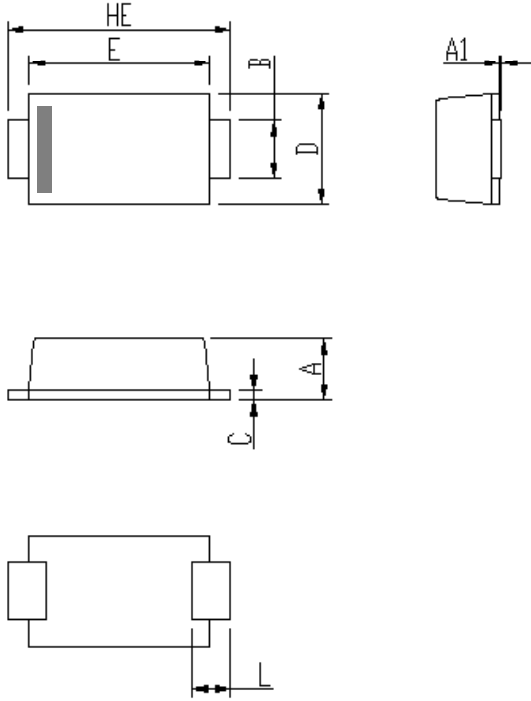


Figure 5. Typical Junction Capacitance

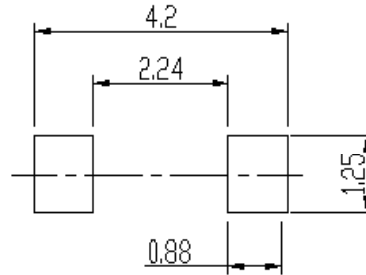
## Package Outline Dimensions

eSGA (SOD-123FL)



| DIM | Unit: mm |      | Unit: inch |       |
|-----|----------|------|------------|-------|
|     | MIN      | MAX  | MIN        | MAX   |
| A   | 0.9      | 1.08 | 0.035      | 0.043 |
| A1  | 0        | 0.1  | 0.000      | 0.004 |
| B   | 0.85     | 1.05 | 0.033      | 0.041 |
| C   | 0.1      | 0.25 | 0.004      | 0.010 |
| D   | 1.7      | 2    | 0.067      | 0.079 |
| E   | 2.9      | 3.1  | 0.114      | 0.122 |
| L   | 0.43     | 0.83 | 0.017      | 0.033 |
| HE  | 3.5      | 3.9  | 0.138      | 0.154 |

Soldering footprint



## Packing Information

### Packing quantities

3000 pcs/Reel, 40 Reels/Box; 8mm Tape, 7" Reel

### Tape & Reel Spec

